

NLSV1T34

1-Bit Dual-Supply Non-Inverting Level Translator

The NLSV1T34 is a 1-bit configurable dual-supply voltage level translator. The input A_n and output B_n ports are designed to track two different power supply rails, V_{CCA} and V_{CCB} respectively. Both supply rails are configurable from 0.9 V to 4.5 V allowing universal low-voltage translation from the input A_n to the output B_n port.

Features

- Wide V_{CCA} and V_{CCB} Operating Range: 0.9 V to 4.5 V
- High-Speed w/ Balanced Propagation Delay
- Inputs and Outputs have OVT Protection to 4.5 V
- Non-preferential V_{CCA} and V_{CCB} Sequencing
- Power-Off Protection
- Power-Off High Impedance Inputs and Outputs
- Ultra-Small Packaging: 1.45 mm x 1.0 mm ULLGA6
2.0 mm x 2.1 mm SC-88A
1.2 mm x 1.0 mm UDFN6
1.45 mm x 1.0 mm UDFN6
- These are Pb-Free Devices

Typical Applications

- Mobile Phones, PDAs, Other Portable Devices

Important Information

- ESD Protection for All Pins:
HBM (Human Body Model) > 3000 V

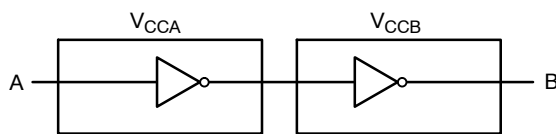







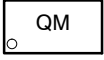

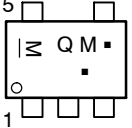
Figure 1. Logic Diagram



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MARKING DIAGRAMS

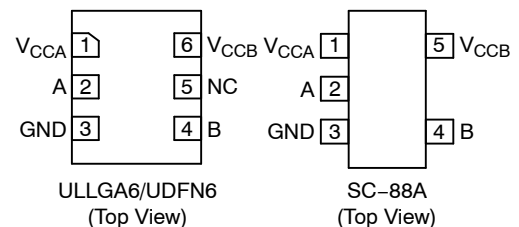
	UDFN6 MU SUFFIX CASE 517AA	
	UDFN6 MU SUFFIX CASE 517AQ	
	ULLGA6 MX1 SUFFIX CASE 613AF	
	SC-88A (SOT-353/SC-70) DF SUFFIX CASE 419A	

Q, A = Device Code
M = Date Code*
▪ = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

PIN ASSIGNMENT



ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

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PIN ASSIGNMENT

PIN	FUNCTION
V _{CCA}	Input Port DC Power Supply
V _{CCB}	Output Port DC Power Supply
GND	Ground
A	Input Port
B	Output Port

TRUTH TABLE

INPUTS	OUTPUTS
A	B
L	L
H	H

MAXIMUM RATINGS

Symbol	Rating	Value	Condition	Unit
V _{CCA} , V _{CCB}	DC Supply Voltage	-0.5 to +5.5		V
V _I	DC Input Voltage	-0.5 to +5.5	A	V
V _O	DC Output Voltage (Power Down)	-0.5 to +5.5	B V _{CCA} = V _{CCB} = 0	V
	(Active Mode)	-0.5 to +5.5	B	V
I _{IK}	DC Input Diode Current	-20	V _I < GND	mA
I _{OK}	DC Output Diode Current	-50	V _O < GND	mA
I _O	DC Output Source/Sink Current	±50		mA
I _{CCA} , I _{CCB}	DC Supply Current Per Supply Pin	±100		mA
I _{GND}	DC Ground Current per Ground Pin	±100		mA
T _{STG}	Storage Temperature	-65 to +150		°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CCA} , V _{CCB}	Positive DC Supply Voltage	0.9	4.5	V
V _I	Bus Input Voltage	GND	4.5	V
V _{IO}	Bus Output Voltage (Power Down Mode)	GND	4.5	V
	(Active Mode)	GND	V _{CCB}	V
T _A	Operating Temperature Range	-40	+85	°C
Δt / ΔV	Input Transition Rise or Rate V _I , from 30% to 70% of V _{CC} ; V _{CC} = 3.3 V ±0.3 V	0	10	nS

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DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test Conditions	V _{CCA} (V)	V _{CCB} (V)	-40°C to +85°C		Unit
					Min	Max	
V _{IH}	Input HIGH Voltage		3.6 – 4.5	0.9 – 4.5	2.2	–	V
			2.7 – 3.6		2.0	–	
			2.3 – 2.7		1.6	–	
			1.4 – 2.3		0.65 * V _{CCA}	–	
			0.9 – 1.4		0.9 * V _{CCA}	–	
V _{IL}	Input LOW Voltage		3.6 – 4.5	0.9 – 4.5	–	0.8	V
			2.7 – 3.6		–	0.8	
			2.3 – 2.7		–	0.7	
			1.4 – 2.3		–	0.35 * V _{CCA}	
			0.9 – 1.4		–	0.1 * V _{CCA}	
V _{OH}	Output HIGH Voltage	I _{OH} = -100 μA; V _I = V _{IH}	0.9 – 4.5	0.9 – 4.5	V _{CCB} - 0.2	–	V
		I _{OH} = -0.5 mA; V _I = V _{IH}	0.9	0.9	0.75 * V _{CCB}	–	
		I _{OH} = -2 mA; V _I = V _{IH}	1.4	1.4	1.05	–	
		I _{OH} = -6 mA; V _I = V _{IH}	1.65	1.65	1.25	–	
			2.3	2.3	2.0	–	
		I _{OH} = -12 mA; V _I = V _{IH}	2.3	2.3	1.8	–	
			2.7	2.7	2.2	–	
		I _{OH} = -18 mA; V _I = V _{IH}	2.3	2.3	1.7	–	
3.0	3.0		2.4	–			
V _{OL}	Output LOW Voltage	I _{OL} = 100 μA; V _I = V _{IL}	0.9 – 4.5	0.9 – 4.5	–	0.2	V
		I _{OL} = 0.5 mA; V _I = V _{IH}	1.1	1.1	–	0.3	
		I _{OL} = 2 mA; V _I = V _{IH}	1.4	1.4	–	0.35	
		I _{OL} = 6 mA; V _I = V _{IL}	1.65	1.65	–	0.3	
			2.3	2.3	–	0.4	
		I _{OL} = 12 mA; V _I = V _{IL}	2.7	2.7	–	0.4	
			2.3	2.3	–	0.6	
		I _{OL} = 18 mA; V _I = V _{IL}	3.0	3.0	–	0.4	
3.0	3.0		–	0.55			
I _I	Input Leakage Current	V _I = V _{CCA} or GND	0.9 – 4.5	0.9 – 4.5	-1.0	1.0	μA
I _{CCA}	Quiescent Supply Current	V _I = V _{CCA} or GND; I _O = 0, V _{CCA} = V _{CCB}	0.9 – 4.5	0.9 – 4.5	–	2.0	μA
I _{CCB}	Quiescent Supply Current	V _I = V _{CCA} or GND; I _O = 0, V _{CCA} = V _{CCB}	0.9 – 4.5	0.9 – 4.5	–	2.0	μA
I _{CCA} + I _{CCB}	Quiescent Supply Current	V _I = V _{CCA} or GND; I _O = 0, V _{CCA} = V _{CCB}	0.9 – 4.5	0.9 – 4.5	–	4.0	μA
I _{OFF}	Power OFF Leakage Current	V _I = 4.5 V	0	0	–	5.0	μA

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TOTAL STATIC POWER CONSUMPTION ($I_{CCA} + I_{CCB}$)

V_{CCA} (V)	-40°C to +85°C										Unit
	V_{CCB} (V)										
	4.5		3.3		2.8		1.8		0.9		
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
4.5		2		2		2		2		< 1.5	μ A
3.3		2		2		2		2		< 1.5	μ A
2.8		< 2		< 1		< 1		< 0.5		< 0.5	μ A
1.8		< 1		< 1		< 0.5		< 0.5		< 0.5	μ A
0.9		< 0.5		< 0.5		< 0.5		< 0.5		< 0.5	μ A

NOTE: Connect ground before applying supply voltage V_{CCA} or V_{CCB} . This device is designed with the feature that the power-up sequence of V_{CCA} and V_{CCB} will not damage the IC.

AC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	V_{CCA} (V)	-40°C to +85°C										Unit
			V_{CCB} (V)										
			4.5		3.3		2.8		1.8		1.2		
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
t_{PLH} , t_{PHL} (Note 1)	Propagation Delay, A to B	4.5		1.6		1.8		2.0		2.1		2.3	nS
		3.3		1.7		1.9		2.1		2.3		2.6	
		2.8		1.9		2.1		2.3		2.5		2.8	
		1.8		2.1		2.4		2.5		2.7		3.0	
		1.2		2.4		2.7		2.8		3.0		3.3	

1. Propagation delays defined per Figure 2.

CAPACITANCE

Symbol	Parameter	Test Conditions	Typ (Note 2)	Unit
$C_{I/O}$	I/O Pin Input Capacitance	$V_{CCA} = V_{CCB} = 3.3$ V, $V_I = 0$ V or $V_{CCA/B}$	5.0	pF
C_{PD}	Power Dissipation Capacitance	$V_{CCA} = V_{CCB} = 3.3$ V, $V_I = 0$ V or V_{CCA} , $f = 10$ MHz	5.0	pF

2. Typical values are at $T_A = +25^\circ\text{C}$.

3. C_{PD} is defined as the value of the IC's equivalent capacitance from which the operating current can be calculated from:
 $I_{CC(\text{operating})} \cong C_{PD} \times V_{CC} \times f_{IN}$ where $I_{CC} = I_{CCA} + I_{CCB}$.

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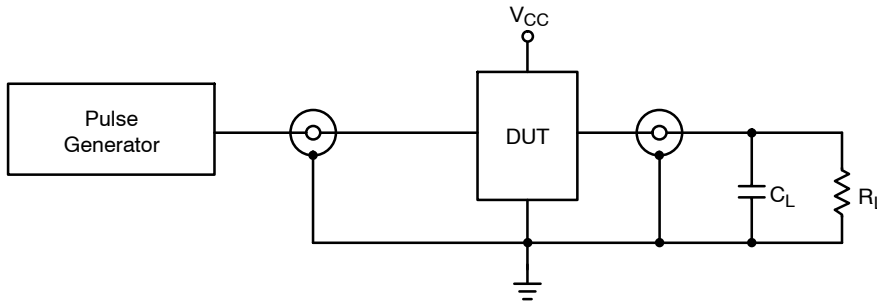
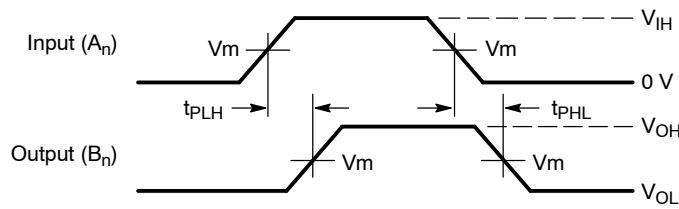


Figure 2. AC (Propagation Delay) Test Circuit

Test	Switch
$C_L = 15 \text{ pF}$ or equivalent (includes probe and jig capacitance)	
$R_L = 2 \text{ k}\Omega$ or equivalent	
Z_{OUT} of pulse generator = 50Ω	



Waveform 1 – Propagation Delays

$t_R = t_F = 2.0 \text{ ns}$, 10% to 90%; $f = 1 \text{ MHz}$; $t_W = 500 \text{ ns}$

Figure 3. AC (Propagation Delay) Test Circuit Waveforms

Symbol	V_{CC}
	0.9 V – 4.5 V
V_{mA}	$V_{CCA}/2$
V_{mB}	$V_{CCB}/2$

ORDERING INFORMATION

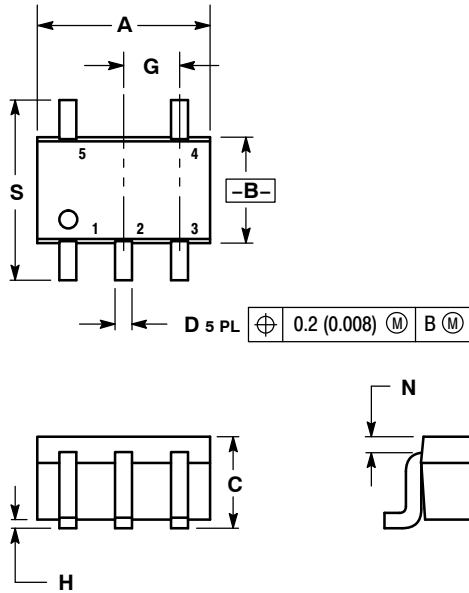
Device	Package	Shipping [†]
NLSV1T34MUTBG	UDFN6 (Pb-Free)	3000 / Tape & Reel
NLSV1T34AMUTCG	UDFN6 (Pb-Free)	3000 / Tape & Reel
NLSV1T34AMX1TCG	ULLGA6 (Pb-Free)	3000 / Tape & Reel
NLSV1T34DFT2G	SC-88A (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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PACKAGE DIMENSIONS

SC-88A, SOT-353, SC-70
CASE 419A-02
ISSUE J

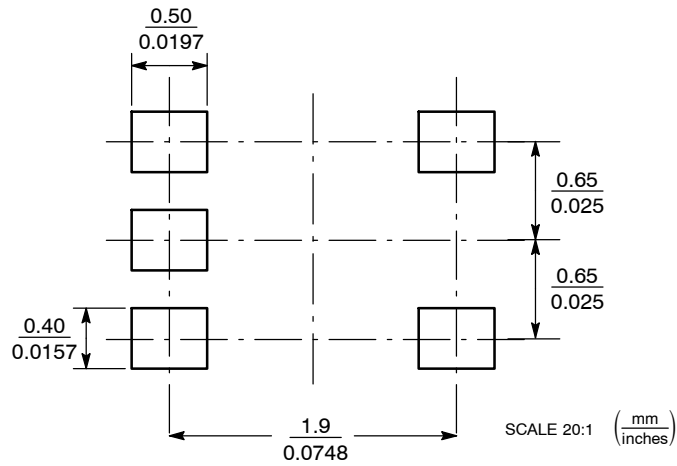


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. 419A-01 OBSOLETE. NEW STANDARD 419A-02.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.071	0.087	1.80	2.20
B	0.045	0.053	1.15	1.35
C	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026 BSC		0.65 BSC	
H	---	0.004	---	0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
N	0.008 REF		0.20 REF	
S	0.079	0.087	2.00	2.20

SOLDERING FOOTPRINT*

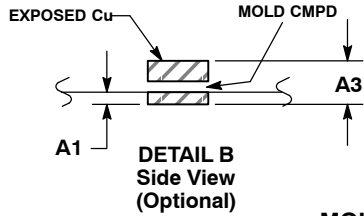
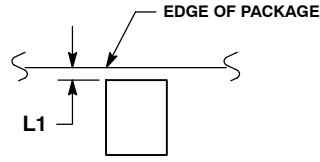
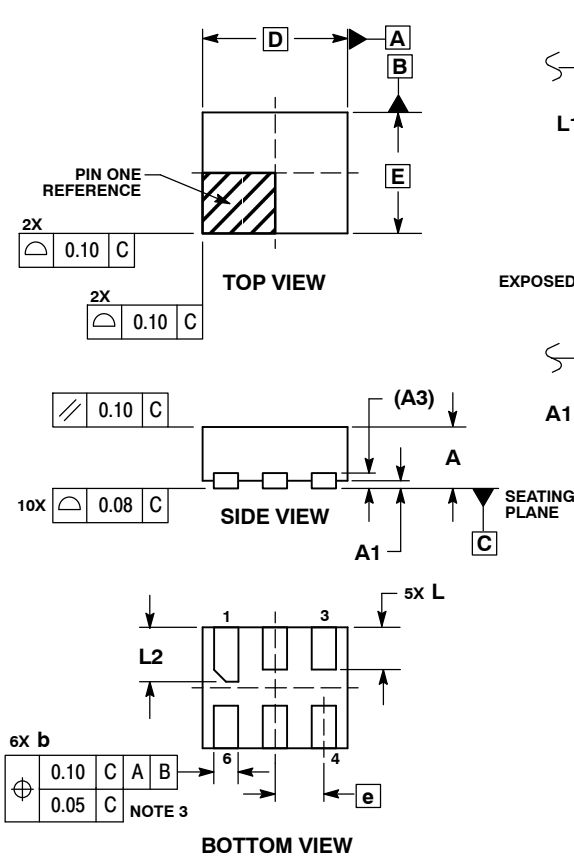


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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PACKAGE DIMENSIONS

UDFN6, 1.2x1.0, 0.4P
CASE 517AA-01
ISSUE C

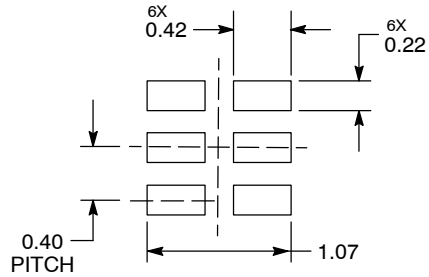


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 mm FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.127	REF
b	0.15	0.25
D	1.20 BSC	
E	1.00 BSC	
e	0.40 BSC	
L	0.30	0.40
L1	0.00	0.15
L2	0.40	0.50

MOUNTING FOOTPRINT*



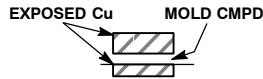
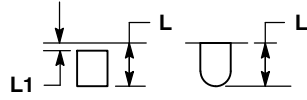
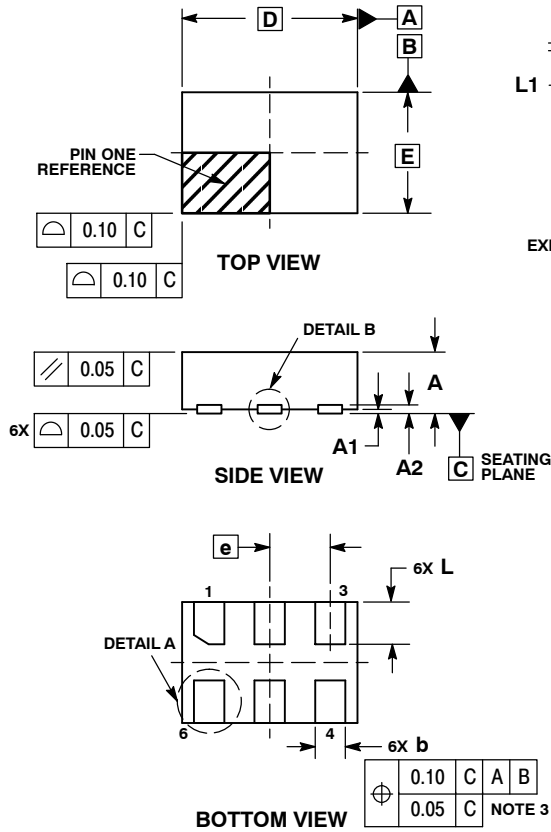
DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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PACKAGE DIMENSIONS

UDFN6, 1.45x1.0, 0.5P
CASE 517AQ-01
ISSUE O

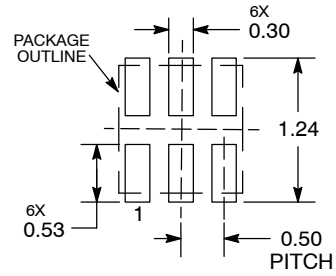


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.

MILLIMETERS		
DIM	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A2	0.07 REF	
b	0.20	0.30
D	1.45 BSC	
E	1.00 BSC	
e	0.50 BSC	
L	0.30	0.40
L1	---	0.15

MOUNTING FOOTPRINT



DIMENSIONS: MILLIMETERS

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